



BGO827; BGO827/FC0; BGO827/SC0

870 MHz optical receivers

Rev. 5 — 29 September 2010

Product data sheet

1. Product profile

1.1 General description

High dynamic range optical receiver amplifier modules in a standard SOT115 package where the non-jacketed fiber has either no connector or has an FC/APC or SC/APC connector.

The amplifier supply voltage pin and the photodiode bias voltage pin both connect to 24 V (DC).

The modules have a mono mode optical input suitable for 1 290 nm to 1 600 nm wavelengths, a terminal to monitor the photodiode current and an electrical output having a characteristic impedance of 75 Ω .

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Therefore care should be taken during transport and handling.

1.2 Features and benefits

- Excellent linearity
- Low noise
- Excellent flatness
- Standard CATV outline
- Rugged construction
- Gold metallization ensures excellent reliability
- High optical input power range

1.3 Applications

- CATV optical node systems operating in the 40 MHz to 870 MHz frequency range.



1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f	frequency range		40	-	870	MHz
S ₂₂	output return losses	f = 40 MHz to 870 MHz	11	-	-	dB
	optical input return losses		45	-	-	dB
d ₂	second order distortion	f = 854.5 MHz	-	-	-57	dB
F	equivalent noise input	f = 40 MHz to 870 MHz	-	-	8.5	pA/√Hz
I _{tot}	total current consumption (DC)	V _B = 24 V	175	-	205	mA

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
BGO827 (SOT115T)			
1	monitor current		
2, 3	common		
4	+V _B of the photodiode		
5	+V _B of the amplifier		
7, 8	common		
9	output		
BGO827/FC0 (SOT115X)			
1	monitor current		
2, 3	common		
4	+V _B of the photodiode		
5	+V _B of the amplifier		
7, 8	common		
9	output		
BGO827/SC0 (SOT115Y)			
1	monitor current		
2, 3	common		
4	+V _B of the photodiode		
5	+V _B of the amplifier		
7, 8	common		
9	output		

3. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
BGO827	-	rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 × 6-32 UNC and 2 extra horizontal mounting holes; optical input; 8 gold-plated in-line leads	SOT115T
BGO827/FC0	-	rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 × 6-32 UNC and 2 extra horizontal mounting holes; optical input with connector; 8 gold-plated in-line leads	SOT115X
BGO827/SC0	-	rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 × 6-32 UNC and 2 extra horizontal mounting holes; optical input with connector; 8 gold-plated in-line leads	SOT115Y

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
f	frequency range		40	870	MHz
T _{stg}	storage temperature		-40	+85	°C
T _{mb}	mounting base temperature		-20	+85	°C
P _{in}	optical input power	continuous	-	5	mW
ESD	ESD sensitivity	human body model; R = 1.5 kΩ; C = 100 pF	500	-	V

5. Characteristics

Table 5. Characteristics

Bandwidth 40 MHz to 870 MHz; V_B = 24 V; T_{mb} = 30 °C; Z_L = 75 Ω.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
S	responsivity						
		BGO827	λ = 1300 nm	800	-	-	V/W
		BGO827/FC0; BGO827/SC0		750	-	-	V/W
ΔS	responsivity difference	responsivity at T _{mb} = 85 °C – responsivity at T _{mb} = 30 °C; f = 870 MHz	-	-50	-	V/W	
FL	flatness straight line (peak to valley)	f = 40 MHz to 870 MHz	-	-	1	dB	
SL	slope straight line	f = 40 MHz to 870 MHz	0	-	2	dB	
ΔSL	slope difference	slope at T _{mb} = 85 °C – slope at T _{mb} = 30 °C	-	-0.35	-	dB	
S ₂₂	output return losses	f = 40 MHz to 870 MHz	11	-	-	dB	
	optical input return losses		45	-	-	dB	

Table 5. Characteristics ...continued

Bandwidth 40 MHz to 870 MHz; $V_B = 24\text{ V}$; $T_{mb} = 30\text{ }^\circ\text{C}$; $Z_L = 75\text{ }\Omega$.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
d_2	second order distortion	$f_m = 446.5\text{ MHz}$	[1][2]	-	-	-68	dB
		$f_m = 746.5\text{ MHz}$	[1][3]	-	-	-63	dB
		$f_m = 854.5\text{ MHz}$	[1][4]	-	-	-57	dB
Δd_2	second order distortion difference	d_2 at $T_{mb} = 85\text{ }^\circ\text{C}$ - d_2 at $T_{mb} = 30\text{ }^\circ\text{C}$	-	2.5	-	dB	
		d_2 at $T_{mb} = -20\text{ }^\circ\text{C}$ - d_2 at $T_{mb} = 30\text{ }^\circ\text{C}$	-	-1.5	-	dB	
d_3	third order distortion	$f_m = 853.25\text{ MHz}$	[5][6]	-	-	-73	dB
Δd_3	third order distortion difference	d_3 at $T_{mb} = 85\text{ }^\circ\text{C}$ - d_3 at $T_{mb} = 30\text{ }^\circ\text{C}$	-	1	-	dB	
		d_3 at $T_{mb} = -20\text{ }^\circ\text{C}$ - d_3 at $T_{mb} = 30\text{ }^\circ\text{C}$	-	-1	-	dB	
F	equivalent noise input	$f = 40\text{ MHz to }450\text{ MHz}$	-	-	7	$\text{pA}/\sqrt{\text{Hz}}$	
		$f = 450\text{ MHz to }750\text{ MHz}$	-	-	8	$\text{pA}/\sqrt{\text{Hz}}$	
		$f = 750\text{ MHz to }870\text{ MHz}$	-	-	8.5	$\text{pA}/\sqrt{\text{Hz}}$	
s_λ	spectral sensitivity	$\lambda = 1310 \pm 20\text{ nm}$	0.85	-	-	A/W	
		$\lambda = 1550 \pm 20\text{ nm}$	0.9	-	-	A/W	
λ	optical wavelength		1290	-	1600	nm	
L	length of optical fiber	SM type; 9/125 μm					
		BGO827	1	-	-	m	
		BGO827/FC0; BGO827/SC0	746	-	861	mm	
I_{tot}	total current consumption (DC)		175	-	205	mA	
I_{bias}	diode bias current at pin 4 (DC)		-	-	25	mA	

- [1] Two laser test; each laser with a modulation index of 40 %; $P_{opt} = 1\text{ mW}$ (total)
- [2] $f_m = 446.5\text{ MHz}$; $f_p = 97.25\text{ MHz}$; $f_q = 349.25\text{ MHz}$
- [3] $f_m = 746.5\text{ MHz}$; $f_p = 133.25\text{ MHz}$; $f_q = 613.25\text{ MHz}$
- [4] $f_m = 854.5\text{ MHz}$; $f_p = 133.25\text{ MHz}$; $f_q = 721.25\text{ MHz}$
- [5] Three laser test; each laser with a modulation index of 60 %; $P_{opt} = 1\text{ mW}$ (total)
- [6] $f_m = 853.25\text{ MHz}$; $f_p = 133.25\text{ MHz}$; $f_q = 265.25\text{ MHz}$; $f_r = 721.25\text{ MHz}$

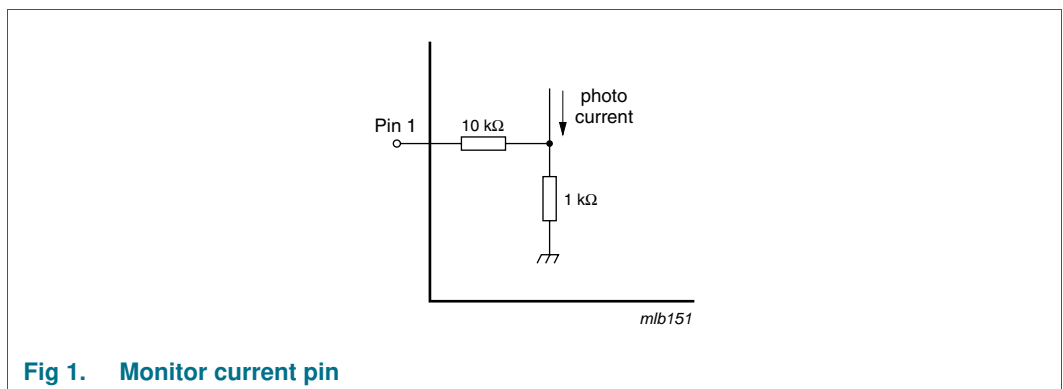
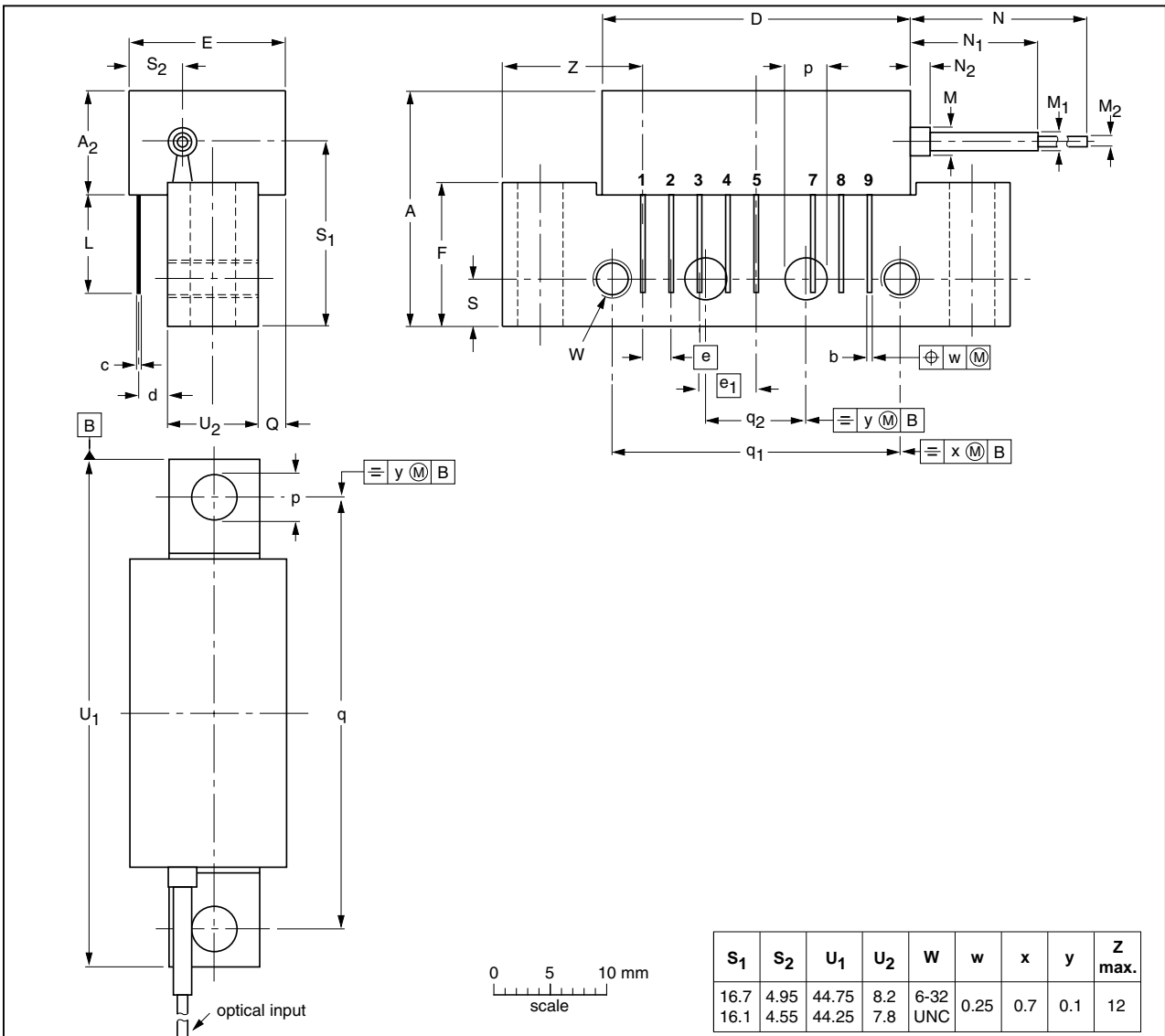


Fig 1. Monitor current pin

6. Package outline

Rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 x 6-32 UNC and 2 extra horizontal mounting holes; optical input; 8 gold-plated in-line leads

SOT115T



S ₁	S ₂	U ₁	U ₂	W	w	x	y	Z max.
16.7	4.95	44.75	8.2	6-32	0.25	0.7	0.1	12
16.1	4.55	44.25	7.8	UNC				

DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₂ max.	b	c	D max.	d max.	E max.	e	e ₁	F	L min.	M	M ₁	M ₂	N min.	N ₁	N ₂	p	Q max.	q	q ₁	q ₂	S
mm	20.8	9.5	0.51 0.38	0.25	27.2	2.54	13.75	2.54	5.08	12.7	8.8	2.5	1.6	0.9	1000	10.7 0.0	5 0	4.15 3.85	2.4	38.1	25.4	10.2	4.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT115T						04-02-04 10-06-18

Fig 2. Package outline SOT115T

Rectangular single-ended package; aluminium flange;
 2 vertical mounting holes; 2 x 6-32 UNC and 2 extra horizontal mounting holes;
 optical input with connector; 8 gold-plated in-line leads

SOT115X

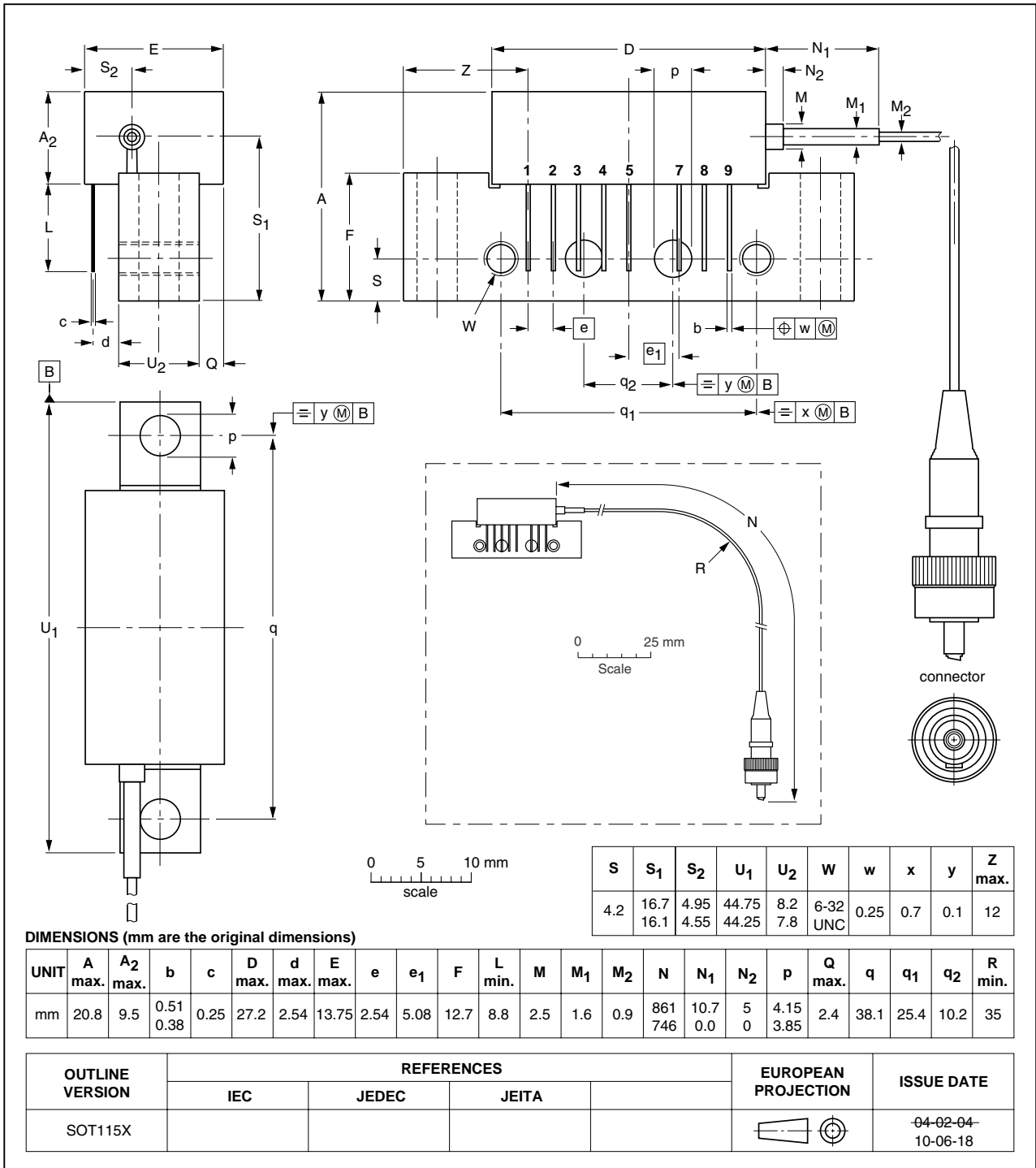


Fig 3. Package outline SOT115X

Rectangular single-ended package; aluminium flange;
 2 vertical mounting holes; 2 x 6-32 UNC and 2 extra horizontal mounting holes;
 optical input with connector; 8 gold-plated in-line leads

SOT115Y

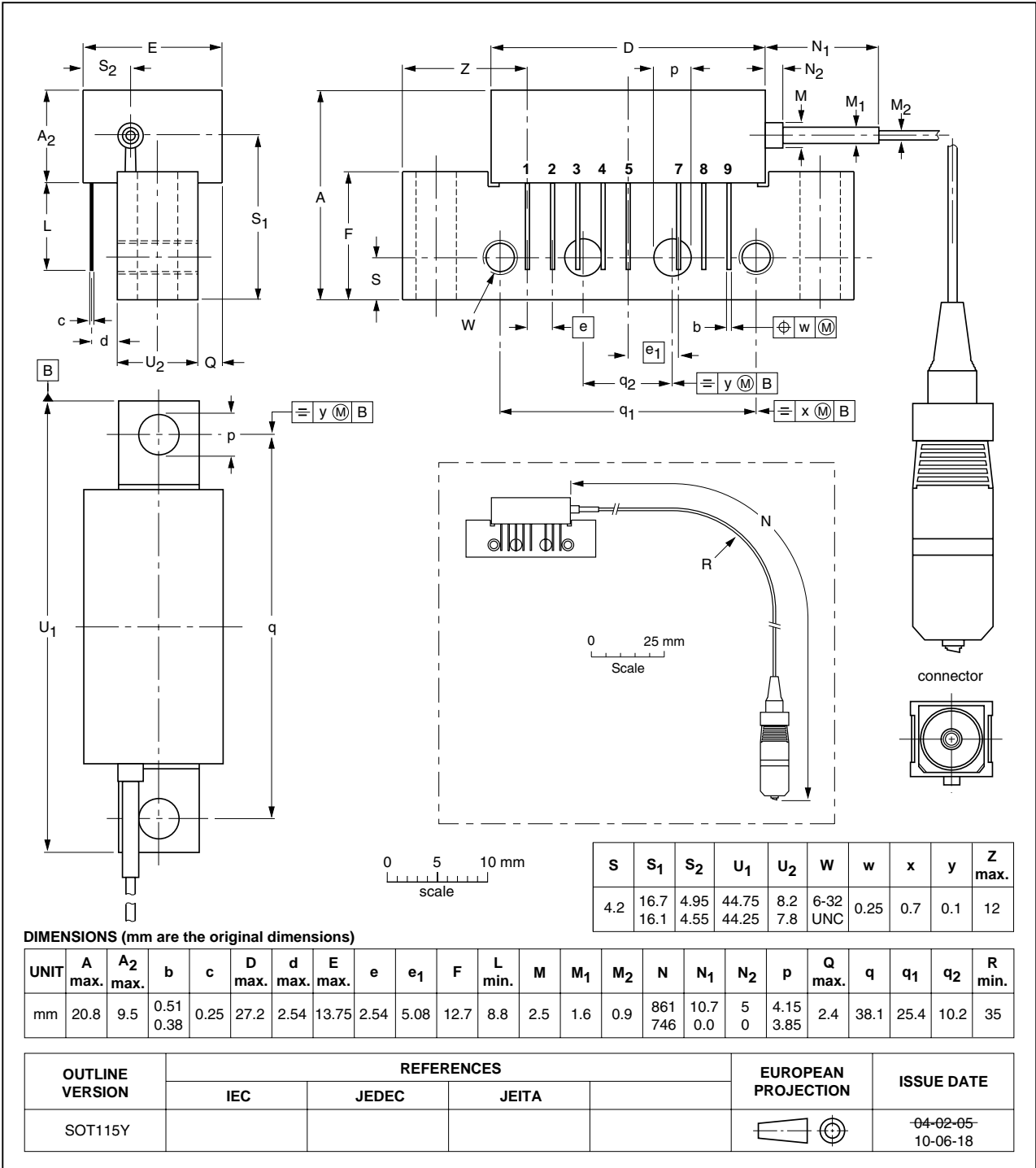


Fig 4. Package outline SOT115Y

7. Handling information

Fiberglass optical coupling: maximum tensile strength = 5 N; minimum bending radius = 35 mm.

8. Revision history

Table 6. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BGO827_FC0_SC0 v.5	20100929	Product data sheet	-	BGO827_FC0_SC0 v.4
Modifications:		<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. Legal texts have been adapted to the new company name where appropriate. Package outline and simplified outline drawings have been updated to the latest version. 		
BGO827_FC0_SC0 v.4 (9397 750 14436)	20050329	Product data sheet	-	BGO827_FC0_SC0 v.3
BGO827_FC0_SC0 v.3 (9397 750 13061)	20040407	Product specification	-	BGO827_FC0_SC0 v.2
BGO827_FC0_SC0 v.2 (9397 750 10522)	20021210	Product specification	-	BGO827_FC0_SC0 v.1
BGO827_FC0_SC0 v.1 (9397 750 09934)	20020627	Product specification	-	-

9. Legal information

9.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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